



Schedule of Scope to Certificate of Approval **Approved Process - Capability Approval**

IECQ Certificate No.: IECQ-C BSI 14.0012

CB Certificate No.: E090/CA

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Finishes: *Electroplated Tin-Lead
 *Hot Air Solder Levelling
 *Lead Free Hot air solder level
 *Electroless Nickel/Gold;
 *Immersion Tin
 *Immersion Silver
 2.5µm Gold on 5µm Nickel Edge Contacts
 2.5µm Gold on Copper Edge Contacts
 Copper in plated through holes 20µm minimum
 Photoimageable Legend
 Photoimageable resist

Additional: Landless holes

* These features meet the requirements for accelerated ageing when tested in accordance with BS 6221 Part 2,14a.